

Minutes of the CE-2.2 Subcommittee Connector and Socket Specifications
28 – 29 April 2009
New Orleans, LA

1. Approval of the 6 – 7 October 2008 minutes

2. TEST PROCEDURE PROJECTS (BY PROJECT NUMBER)

"If any SP listed below receives insufficient votes for approval, the committee may approve the document for EDEC ballot at this meeting. It is the responsibility of the member to submit comments in writing prior to the meeting".

A. SP-4965, EIA-540B0AE, Detail Land Grid Array (Carl Fritz)

Sent letter (mccwil365) to EIA for EDEC ballot to reaffirm on 5 December 2008.

Standard was published as reaffirmed on 13 January 2009 and received by US Mail on 26 January 2009.

B. SP-4970, EIA-540DAAA-A, Detail, DIP

Sent second letter was sent to EIA to process the EDEC ballot on 6 October 2005.

C. SP-4971: EIA-700A0AB: 68-pin Memory Card Connector

Sent second letter was sent to EIA to process the EDEC ballot on 6 October 2005.

D. SP-4973: EIA-540B0AB: Low Pin Count BGA

Carl reported that he sent memo (mccwil347) to EIA requesting that the project and specification be cancelled on 2 May 2008 on behalf of Max Peel.

Project cancelled per Cecelia Yates at EIA on 13 May 2008. Cecelia indicated that this specification was actually issued as a letter ballot on 24 January 2002 by Tom Peel.

E. SP-5112 as follows:

- EIA-700A0AC: Detail, 88-pin DRAM Connector
- EIA-540A000-A: Sectional, Chip Carrier Sockets
- EIA-540AA00: Blank, Leadless Chip Carrier Sockets
- EIA-540AAAA: Detail, Type A Chip Carrier Sockets
- EIA-540AB00: Blank, PQFP
- EIA-540ABAA: Detail, PQFP
- EIA-540AC00: Blank, PCC
- EIA-540ACAA: Detail, PCC
- EIA-540AD00: Blank, Adaptor QFP to PGA

- EIA-540B000: Sectional, PGA
- EIA-540BA00: Blank, PGA
- EIA-540BAAB: Detail, Non-Mechanical PGA
- EIA-540BAAC: Detail, Flex Carrier PGA
- EIA-540D000-A: Sectional, In-Line Packages
- EIA-540DA00: Blank, DIP (Will be sent out for review)
- EIA-540DAAB: Detail, Flex Carrier DIP
- EIA-540EA00: Blank, Round Sockets
- EIA-540EAAA: Detail, Round Sockets
- EIA-540F000: Sectional, Multi-Package Modules

A second letter (mccwil269) was sent to Cecelia Yates (EIA Staff) EDEC ballot on 14 August 2006.

F. PN-5123, EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets (Contech Research, Tom Peel)

Carl reported that he sent memo (mccwil348) to EIA requesting that the project and specification be cancelled on 2 May 2008 on behalf of Tom Peel.

3. New Business

A. New Specification (Requested by Frank Ruffino)

Please add a proposed new connector standard for the "Mini-Change A-Size (2-6 pole)" connector. Yes, a new connector standard!

B. Connector Specifications Past Due for 5-Year Review

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due
7000000	A	Generic Specification for Electronic and Electrical Connectors of Certified Quality (for Frequencies Essentially Below 3 MHz)	August-96	July-01	7
270	I	Tools, Crimping, Solderless Wiring Devices - Recommended Procedures for User Certification	January-62	December-66	42
280	C	Solderless Wrapped Electrical Connections	May-92	May-97	12
297	A	Cable Connectors for Audio Facilities for Radio Broadcasting-Correction Sheet	June-70	May-75	34
380	A	Electrical Connectors, Small Contact Standard for	January-78	December-82	26
406	I	General Document for Connectors, Electric, Printed-Wiring Board-IPC-C-405A	January-74	December-78	30
429	I	Connectors, Electrical Flat Cable Type-IPC FC-218B	January-76	December-80	28
616	A	Detail Specification for 2 Millimeter, Two-Part Connectors for Use with Printed Boards and Backplanes	November-02	November-07	1
622	A	Glossary of Electrical Connector Related Terms	August-07	August-12	-4
700A0AA	I	Detail Specification for 1.27 mm Pitch, Ribbon Contact, Trapezoidal Shaped, Shielded I/O Connector	April-96	April-01	8
700A0AD	I	Detail Specification for the Interface of the 1.27 mm Pitch, Ribbon Contact (Leaf Spring), Trapezoidal Shaped, Self-Locking I/O Connector	November-97	October-02	6
700A0AE	I	Detail Specification for Trapezoidal Connectors with Nonremovable Ribbon Cable Contacts on 1.27mm Pitch Double Row Used with Single Connector Attachments (SCA2)	January-00	December-04	4
700A0AF	I	Detail Specification for Trapezoidal Shielded Connector 0.8 mm Pitch Used with Very High Density Cable Interconnect (VHDCI)	July-00	June-05	4
700AAAB	A	Detail Specification for 1.0 mm, Two-Part Connectors for Use with Parallel Printed Boards	January-96	December-00	8
700B000	I	Sectional Specification for Rectangular/Trapezoidal Connectors of Certified Quality	May-99	May-04	5
700BA00	I	Blank Detail Specification for Rectangular/Trapezoidal Connectors of	September-98	September-03	5

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due
		Certified Quality			
700BAAD		Detail Specification for Shielded Rectangular Connectors for Universal Serial Bus Plus Power Connectors Series "A"	May-00	April-05	4
700BAAE		Detail Specification for Shielded Rectangular Connectors for Universal Serial Bus Plus Power Connectors Series "B"	May-00	April-05	4
700C000		Sectional Specification for Circular Multicontact Connectors of Assessed Quality (for Frequencies Essentially Below 3 MHz)	January-97	January-02	7
700D000		Sectional Specification for Discrete Contacts of Certified Quality (for Use in dc/Low Frequency Analog Applications and in Digital Applications Employing High Speed Data Rates)	January-98	January-03	6
710		Requirements Guide for Space Grade Electrical Connectors	October-97	October-02	6
IS-47		Contact Termination Finish Standard for Surface Mount Devices	July-87	June-92	17
IS-753		Two-Part High Density Blade and Backplane Tuning Fork Connector	February-98	February-03	6
IS-84		Interim Detail Specification for 2.5 mm Two Part Connector for Use in Electronic Equipment	April-92	April-97	12

C. Socket Specifications Past Due for 5-Year Review

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due
540ADAA		Detail Specification for Adaptor-Carrier Quad Flatpack to Pin Grid Array Sockets for Use in Electronic Equipment	February-92	January-97	12
540B0AA	A	Detail Specification for Production Ball Grid Array (BGA) High Pin Count (1089 Pins and Greater) Socket for Use in Electronic Equipment-Revision	October-01	September-06	2
540BAAA	A	Detail Specification for Mechanically Actuated (Zero and Low Insertion Force) Sockets for Pin Grid Array Devices with 2.54 mm X 2.54 mm (0.1 in X 0.1 in) Spacing for Use in Electronic Equipment	August-96	August-01	7
540CAAC	A	Detail Specification for 2 Pole, 10 A Relay Sockets	November-98	November-03	5
540CAAD	A	Detail Specification for 2 Pole, 5 A Relay Sockets	August-99	August-04	4
540CAAE	A	Detail Specification for 3 Pole, 10 A Relay Sockets	August-99	August-04	4
540DB00		Blank Detail Specification for Decoupling Capacitor Dual In-Line Package Sockets	January-93	December-97	11
540DB00		BLANK DETAIL SPEC FOR DIP SOCKETS W/DECOUPLING CAP	June-93	June-98	11
540DBAA		Detail Specification for Decoupling Capacitor Dual In-Line Package Sockets for Use in Electronic Equipment	January-94	December-98	10

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due
540E000		Sectional Specification for Round-Style Sockets for Use in Electronic Equipment	February-93	February-98	11
540FA00	A	Blank Detail Specification for Multi-Package Module Sockets for Use in Electronic Equipment	April-92	March-97	12
540FAAA		Detail Specification for Multi-Package 100 Mil Pitch, Vertical Mounting Format Module Sockets for Use in Electronic Equipment	January-92	December-96	12
540FAAB		Detail Specification for Multi-Package 100 Mil Pitch, Angled Mounting Format Module Sockets for Use in Electronic Equipment	January-92	December-96	12
540FAAC		Detail Specification for Multi-Package 50 Mil Pitch, Vertical Mounting Format Module Sockets for Use in Electronic Equipment	January-92	December-96	12
540FAAD		Detail Specification for Multi-Package 50 Mil Pitch, Angled Mounting Format Module Sockets for Use in Electronic Equipment	January-92	December-96	12
540G000		Sectional Specification for Burn-In Sockets for Use in Electronic Equipment	January-93	December-97	11
540GA00		Blank Detail Specification for Burn-In Sockets for Chip Carrier Packages with Molded Carrier Rings for Use in Electronic Equipment	January-93	December-97	11
540GAAA		Detail Specification for Burn-In Sockets for Chip Carrier Packages with Molded Carrier Rings for Use in Electronic Equipment	January-93	December-97	11
540HA00		Blank Detail Specification for Burn-In Sockets Used with Ball Grid Array Devices for Use in Electronic Equipment	May-00	April-05	4
540HAAA		Detail Specification for Burn-In Sockets Used with Ball Grid Array Devices for Use in Electronic Equipment	June-00	May-05	4
540J000		Sectional Specification for Battery Holders for Use in Electronic Equipment	May-00	April-05	4
540J0AA		Detail Specification for Cylindrical Battery Holders, Standard Profile, for Use in Electronic Equipment	May-00	April-05	4
540J0AB		Detail Specification for Coin Cell Battery Holders for Use in Electronic Equipment	June-01	May-06	3
674	A	Specification for Dimensions and Connectors Locations of Small Form Factor 45 millimeter (1.8 inch) Disk Drive	August-06	August-11	-3
675		Specification for Small Form Factor 33.0 mm (1.3 in) Disk Drives	January-96	December-00	8
676	A	Specification for Parallel 1.8 inch Drive Form Factor (78 millimeter x 54 millimeter)	June-06	June-11	-2
677		Specification for Small Form Factor Power Connector Pin Dimensions	June-97	June-02	7
740		Specification for Small Form Factor 88.9 mm (3.5 in) Disk Drives	July-99	June-04	5
741		Specification for Small Form Factor 133.35 mm (5.25 in) Disk Drives	May-01	April-06	3

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due
773		Check List for Document Development and Revision	May-00	April-05	4
CB-5-1		Recommended Test Procedure for Semiconductor Thermal Dissipating Devices-Addendum to CB5	May-71	April-76	33
IS-701		Production Ball Grid Array (BGA) Socket Test Specification	July-96	July-01	7

D. Unknown Connector Documents

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due	Comments
51		EMISSION LIMITATION AM BROADCAST TRANSMISSION	September-88	August-93		Number unidentifiable
5810000		GENERIC SPEC RECTANGULAR CONNECTOR FOR FREQUENCIES BELOW 3 MHZ				Number unidentifiable
5880000		GEN SPEC PRINTED BD CONNECTORS OF ASSESSED QUALITY				Number unidentifiable
437-1		ADDENDUM NO. 1 TO EIA-437 BASIC SENSITIVE SWITCHES	September-78	August-83		Number unidentifiable
437-2			May-78	April-83		RESCINDED 9/25/89
437-3			September-78	August-83		RESCINDED 9/25/89
437-4			September-89	August-94		RESCINDED 9/25/89
437-5		20 AMP DOUBLE BREAK SENSITIVE SWITCHES	March-81	February-86		Number unidentifiable
437-6		15 AMP DOUBLE BREAK SENSITIVE SWITCHES	March-81	February-86		Number unidentifiable
437-7		10 AMP DOUBLE SENSITIVE SWITCHES	June-80	May-85		Number unidentifiable
437-8		8 AMP DOUBLE SENSITIVE SWITCHES	June-80	June-85		Number unidentifiable
64		INTERIM STD, 2MM TWO-PART CONN FOR PRINT WIRING BD	March-91	March-96		Number unidentifiable
700A000		SECT SPEC FOR PRINTED BOARD CONNECTORS ESSENTIALLY BELOW 3MHZ				No record that specification was ever issued
700A0AG		DT SP TRAPEZOIDAL PIN-AND-SOCKET CONN FIBER CHANNEL APPLICATIONS				No record that specification was ever issued
700AAAA		DT SP 1.27 mm PITCH RIBBON CONTACT TRAPEZOIDAL SHIELDED I/O CONNC				No record that specification was ever issued
700BAAA		CONNECTOR ELECT RECTANGULAR SCOOP-PROOF LOW FORCE SUBMINIATURE				No record that specification was ever issued
700BAAB		CONNECTORS, ELECTRICAL, RECTANGULAR, BLIND-MATE, SCOOP-PROOF				No record that specification was ever issued
700BAAC		DT SP BLIND-MATE, SCOOP PROOF EVA LOW EARTH ORBIT LEO CONNECTOR				No record that specification was ever issued

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due	Comments
700D0AA		HIGH DENSITY TUNING FORK COMPONENTS				No record that specification was ever issued
700DA00		DISCRETE CONTACT BLANK DETAIL SPECIFICATION				No record that specification was ever issued

E. Unknown Socket Documents

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due	Comments
540B0AB		Low Pin Count BGA				Sent letter to EIA to cancel project on 13 May 2008
540D0AA		DET. SPEC - SOCKETS FOR DUAL...PACKAGES	January-90	January-95		No record that specification was ever issued
540F0AG		DETAIL SPEC-SMALL OUTLINE DIMM DUAL-IN-LINE MEMORY MODULE SOCKETS				No record that specification was ever issued
540FAAE		DT SP DUAL IN-LINE MEMORY (DIMM) SOCKETS 1.27 MM VERTICAL MOUNT				No record that specification was ever issued
540FAAF		DT SP 8-BYTE 168 POSITION DUAL IN-LINE MEMORY MODULE SOCKET 1.27				No record that specification was ever issued
540JAAA		DT SP BURN-IN SOCKETS USE W/BALL GRID ARRAY DEVICE USE IN ELEC EQ				No record that specification was ever issued

Prepared by:

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